IN THE CLAIMS:

1. (Canceled)

2. (Previously Amended) A semiconductor wafer having at least one region carrying information for identification, characterized in that the information for identification is provided by magnetic means, wherein the magnetic means comprise magnetic ions that are implanted into the semiconductor wafer.

3-9 (Canceled)

10. (Previously Amended) A method of providing on a semiconductor wafer at least one region carrying information for identification, comprising:

providing a semiconductor wafer; and

providing the at least one region with magnetic means, wherein the magnetic means are provided by ion implantation of magnetic ions.

11-15 (Canceled)

16-30 (Previously Canceled)

31. (Previously Added) The semiconductor wafer according to claim 2, wherein the magnetic means are covered with at least one film layer.

32. (Previously Added) The semiconductor wafer according to claim 2, wherein the magnetic means are proximate a semiconductor wafer edge.

33. (Previously Added) The semiconductor wafer according to claim 2, wherein the magnetic means are proximate an inner region of a semiconductor wafer surface, where a vacuum chuck having magnetic reading capabilities may engage the semiconductor wafer.

34-36 (Canceled)

37. (Previously Added) The method according to claim 10, further comprising covering the magnetic means with at least one film layer.